



Product Change Notification: ALAN-23NWPP173

Date:

26-Jun-2025

Product Category:

Analog to Digital Converters, Digital Temperature Sensors, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Regulators, Power Management - System Supervisors/Voltage Detectors

Notification Subject:

CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

Affected CPNs:

[ALAN-23NWPP173_Affected_CPN_06262025.pdf](#)

[ALAN-23NWPP173_Affected_CPN_06262025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu
Die Attach Material	8900NC	8900NC
Molding Compound Material	G600V	G600V
Lead-Frame Material	A194	A194
DAP Surface Prep	Ag Spot Plated	Ag Single Ring Plated
Lead-Frame Treatment	None	BOT

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 19 August 2025 (date code: 2534)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2025					>	August 2025				
Work Week	23	24	25	26	27		31	32	33	34	35
Qual Report Availability				X							
Final PCN Issue Date				X							
Estimated Implementation Date										X	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as

PCN_#_Qual_Report.

Revision History: June 26, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_ALAN-23NWPP173 Qual Report.pdf

PCN_ALAN-23NWPP173_Pre and Post Change_Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

MCP1824T-2502E/OT

MCP1824T-3002E/OT

MCP1824T-3302E/OT

MCP1824T-5002E/OT

MCP6041T-I/OT

MCP6041T-I/OTBAA

MCP6041T-E/OT

MCP6141T-E/OT

MCP601T-I/OT

MCP601T-I/OTAPL

MCP601T-E/OT

MCP6L1T-E/OT

MCP1316T-20LI/OT

MCP1316T-23LI/OT

MCP1316T-24MI/OT

MCP1316MT-20LI/OT

MCP1316MT-20RI/OT

MCP1316MT-23LI/OT

MCP1319T-31QI/OT

MCP1319MT-24QI/OT

MCP1316MT-29JE/OT

MCP1316T-44JE/OT

MCP1316T-44LE/OT

MCP1316T-44NE/OT

MCP1316T-46BE/OT

MCP1316T-46CE/OT

MCP1316T-46FE/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP1316T-46KE/OT

MCP1316T-46LE/OT

MCP1316T-47FE/OT

MCP1316T-25LE/OT

MCP1316T-26JE/OT

MCP1316T-26LE/OT

MCP1316T-27LE/OT

MCP1316T-29AE/OT

MCP1316T-29EE/OT

MCP1316T-29FE/OT

MCP1316T-29LE/OT

MCP1316T-29NE/OT

MCP1316T-30CE/OT

MCP1316T-30FE/OT

MCP1316T-31LE/OT

MCP1316T-31RE/OT

MCP1316T-32LE/OT

MCP1316MT-45GE/OT

MCP1316MT-46FE/OT

MCP1316MT-46GE/OT

MCP1316MT-46LE/OT

MCP1316MT-26CE/OT

TC1017-2.9VCTTR

TC1017-3.0VCTTR

TC1017-3.3VCTTR

TC1017-4.0VCTTR

TC1017-1.85VCTTR

TC1017-2.85VCTTR

MCP6541UT-E/OT

MCP6546UT-E/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP6231T-E/OT

MCP6G01T-E/OT

MCP6001UT-I/OT

MCP6001UT-E/OT

MCP6L01UT-E/OT

TC2014-1.8VCTTR

TC2014-2.5VCTTR

TC2014-2.6VCTTR

TC2014-2.7VCTTR

TC2014-2.8VCTTR

TC2014-2.85VCTTR

TC2014-3.0VCTTR

TC2014-3.3VCTTR

TC2014-5.0VCTTR

TC2015-1.8VCTTR

TC2015-2.5VCTTR

TC2015-2.6VCTTR

TC2015-2.7VCTTR

TC2015-2.8VCTTR

TC2015-2.85VCTTR

TC2015-3.0VCTTR

TC2015-3.3VCTTR

TC2015-5.0VCTTR

TC2185-1.8VCTTR

TC2185-2.5VCTTR

TC2185-2.6VCTTR

TC2185-2.7VCTTR

TC2185-2.8VCTTR

TC2185-2.85VCTTR

TC2185-3.0VCTTR

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC2185-3.3VCTTR

TC2185-5.0VCTTR

TC2054-1.8VCTTR

MCP1321T-29LE/OT

MCP1321T-29ME/OT

MCP1321T-30LE/OT

MCP1321T-31LE/OT

MCP1322T-44LE/OT

MCP1322T-46EE/OT

MCP1322T-46LE/OT

MCP1322T-27LE/OT

MCP1322T-29CE/OT

MCP1322T-29LE/OT

MCP1322T-31GE/OT

MCP1322T-31LE/OT

MCP1322T-32AE/OT

TC1054-1.8VCT713

TC1054-2.5VCT713

TC1054-2.6VCT713

TC1054-2.7VCT713

TC1054-2.8VCT713

TC1054-2.85VCT713

TC1054-3.0VCT713

TC1054-3.3VCT713

TC1054-3.6VCT713

TC1054-4.0VCT713

TC1054-4.2VCT713

TC1054-5.0VCT713

TC1055-1.8VCT713

TC1055-2.5VCT713

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC1055-2.6VCT713

TC1055-2.7VCT713

TC1055-2.8VCT713

TC1055-2.85VCT713

TC1055-3.0VCT713

TC1055-3.3VCT713

TC1055-3.6VCT713

TC1055-4.0VCT713

TC1055-5.0VCT713

TC1186-1.8VCT713

TC1186-2.5VCT713

TC1186-2.6VCT713

TC1186-2.7VCT713

TC1186-2.8VCT713

TC1186-2.85VCT713

TC1186-3.0VCT713

TC1186-3.3VCT713

TC1186-3.6VCT713

TC1186-4.0VCT713

MCP1316MT-29GE/OT

MCP1316MT-29KE/OT

MCP1316MT-29LE/OT

MCP1316MT-29ME/OT

MCP1316MT-30HE/OT

MCP1316MT-31LE/OT

MCP1316MT-33LE/OT

MCP1317T-46LE/OT

MCP1317T-25LE/OT

MCP1317T-29LE/OT

MCP1317T-31AE/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP1317T-31LE/OT

MCP1317T-31RE/OT

MCP1317T-33LE/OT

MCP1318T-45LE/OT

MCP1318T-46LE/OT

MCP1318T-46ME/OT

MCP1318T-29EE/OT

MCP1318T-29HE/OT

MCP1318T-29LE/OT

MCP1318MT-46BE/OT

MCP1318MT-46LE/OT

MCP1318MT-29BE/OT

MCP1318MT-29EE/OT

MCP1318MT-29LE/OT

MCP1319T-44LE/OT

MCP1319T-46LE/OT

MCP1319T-47QE/OT

MCP1319T-28LE/OT

MCP1319T-29CE/OT

MCP1319T-29LE/OT

MCP1319T-42LE/OT

MCP1319MT-46LE/OT

MCP1319MT-47QE/OT

MCP1319MT-26AE/OT

MCP1319MT-26EE/OT

MCP1319MT-28LE/OT

MCP1319MT-29LE/OT

MCP1319MT-30GE/OT

MCP1319MT-33AE/OT

MCP1318T-29LE/OTV09

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP3221A3T-E/OT

MCP3021A3T-E/OT

TC74A0-3.3VCTTR

TC74A0-5.0VCTTR

TC74A1-3.3VCTTR

TC74A1-5.0VCTTR

TC74A2-3.3VCTTR

TC74A2-5.0VCTTR

TC74A3-3.3VCTTR

TC74A3-5.0VCTTR

TC74A4-3.3VCTTR

TC74A4-5.0VCTTR

TC74A5-3.3VCTTR

TC74A5-5.0VCTTR

TC74A6-3.3VCTTR

TC74A6-5.0VCTTR

TC74A7-3.3VCTTR

TC74A7-5.0VCTTR

MCP6561T-E/OT

MCP3221A4T-E/OT

MCP3021A4T-E/OT

MCP3221A2T-E/OT

MCP3021A2T-E/OT

MCP3221A6T-E/OT

MCP3021A6T-E/OT

MCP3221A5T-I/OT

MCP3021A5T-I/OT

MCP3221A5T-E/OT

MCP3021A5T-E/OT

MCP6441T-E/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP6281T-E/OT

MCP3221A7T-E/OT

MCP3021A7T-E/OT

MCP6401T-H/OT

MCP6406T-H/OT

MCP6401T-E/OT

MCP6021T-E/OT

MCP6021T-E/OTHAZ

MCP6566T-E/OT

MCP6231UT-E/OT

MCP6286T-E/OT

MCP3221A0T-E/OT

MCP3021A0T-E/OT

MCP3221A1T-E/OT

MCP3021A1T-E/OT

MCP6G01UT-E/OT

MCP6401UT-E/OT

MCP6291T-E/OT

MCP6291T-E/OTHAZ

MCP6L91T-E/OT-HCM

MCP6L91T-E/OT

MCP6271T-E/OT

MCP6L71T-E/OT

TC1185-2.95VCT713

TC1014-1.8VCT713

TC1014-2.5VCT713

TC1014-2.6VCT713

TC1014-2.7VCT713

TC1014-2.8VCT713

TC1014-2.85VCT713

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC1014-3.0VCT713

TC1014-3.1VCT713

TC1014-3.3VCT713

TC1014-3.6VCT713

TC1014-4.0VCT713

TC1014-5.0VCT713

TC1015-1.8VCT713

TC1015-2.5VCT713

TC1015-2.6VCT713

TC1015-2.7VCT713

TC1015-2.8VCT713

TC1015-2.85VCT713

TC1015-3.0VCT713

TC1015-3.3VCT713

TC1015-3.6VCT713

TC1015-4.0VCT713

TC1015-5.0VCT713

TC2054-2.5VCTTR

TC2054-2.6VCTTR

TC2054-2.7VCTTR

TC2054-2.8VCTTR

TC2054-2.85VCTTR

TC2054-3.0VCTTR

TC2054-3.3VCTTR

TC2054-5.0VCTTR

TC2055-1.8VCTTR

TC2055-2.5VCTTR

TC2055-2.6VCTTR

TC2055-2.7VCTTR

TC2055-2.8VCTTR

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC2055-2.85VCTTR

TC2055-3.0VCTTR

TC2055-3.3VCTTR

TC2055-5.0VCTTR

TC2186-1.8VCTTR

TC2186-2.5VCTTR

TC2186-2.6VCTTR

TC2186-2.7VCTTR

TC2186-2.8VCTTR

TC2186-2.85VCTTR

TC2186-3.0VCTTR

TC2186-3.3VCTTR

TC2186-5.0VCTTR

TC1189QECTTR

TC1189RECTTR

TC1189SECTTR

TC1189TECTTR

TC1189TECTTRBAA

TC1188QECTTR

TC1188RECTTR

TC1188SECTTR

TC1188TECTTR

MCP6241T-E/OT

MCP6561UT-E/OT

MCP1321T-20LI/OT713

MCP1321T-20LI/OT

MCP1321T-20QI/OT

MCP1321T-43BE/OT

MCP1320T-46BE/OT

MCP1320T-46GE/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

MCP1320T-46KE/OT

MCP1320T-46LE/OT

MCP1320T-46FE/OT

MCP1320T-25LE/OT

MCP1320T-27ME/OT

MCP1320T-29BE/OT

MCP1320T-29FE/OT

MCP1320T-29GE/OT

MCP1320T-29LE/OT

MCP1320T-29ME/OT

MCP1320T-29RE/OT

MCP1320T-30BE/OT

MCP1320T-30FE/OT

MCP1320T-30LE/OT

MCP1320T-19HI/OT

MCP1320T-31KE/OT

MCP1320T-31LE/OT

MCP1320T-41LE/OT

MCP1320T-42EE/OT

MCP1320T-42JE/OT

MCP1321T-46CE/OT

MCP1321T-46FE/OT

MCP1321T-46GE/OT

MCP1321T-46LE/OT

MCP1321T-26GE/OT

MCP1321T-29AE/OT

MCP1321T-29CE/OT

MCP1321T-29DE/OT

MCP1321T-29FE/OT

MCP1321T-29KE/OT

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC1015-2.8VCT713BAB

TC1015-3.3VCT713BAC

TC1015-2.6VCT713BAE

TC1015-2.85VCT713BAF

TC1185-1.8VCT713

TC1185-2.0VCT713

TC1185-2.5VCT713

TC1185-2.6VCT713

TC1185-2.7VCT713

TC1185-2.8VCT713

TC1185-2.85VCT713

TC1185-3.0VCT713

TC1185-3.3VCT713

TC1185-3.6VCT713

TC1185-4.0VCT713

TC1185-4.15VCT713

TC1185-5.0VCT713

MCP606T-I/OT

MCP6241UT-E/OT

TC1070VCT713

TC1070VCT713AA

TC1071VCT713

TC1187VCT713

TC1187VCT713AAA

TC1187VCTMR

TC1016-1.8VCTTR

TC1016-1.85VCTTR

TC1017-2.0VCTTR

TC1016-2.6VCTTR

TC1016-2.7VCTTR

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC1016-2.8VCTTR

TC1016-2.85VCTTR

TC1016-2.9VCTTR

TC1016-3.0VCTTR

TC1016-3.3VCTTR

TC1016-4.0VCTTR

TC1017-1.8VCTTR

TC1017-1.9VCTTR

TC1017-2.5VCTTR

TC1017-2.6VCTTR

TC1017-2.7VCTTR

TC1017-2.8VCTTR

TC1186-5.0VCT713

TC1224-1.8VCTTR

TC1224-2.5VCTTR

TC1224-2.6VCTTR

TC1224-2.7VCTTR

TC1224-2.8VCTTR

TC1224-2.85VCTTR

TC1224-3.0VCTTR

TC1224-3.3VCTTR

TC1224-3.6VCTTR

TC1224-4.0VCTTR

TC1224-5.0VCTTR

TC1223-1.8VCTTR

TC1223-2.5VCTTR

TC1223-2.6VCTTR

TC1223-2.7VCTTR

TC1223-2.8VCTTR

TC1223-2.85VCTTR

Date: Wednesday, June 25, 2025

ALAN-23NWPP173 - CCB 7348.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.

TC1223-3.0VCTTR

TC1223-3.3VCTTR

TC1223-3.6VCTTR

TC1223-4.0VCTTR

TC1223-4.2VCTTR

TC1223-5.0VCTTR

MCP1824T-ADJE/OTAAA

MCP1824T-ADJE/OT

MCP1824T-0802E/OT

MCP1824T-1202E/OT

MCP1824T-1802E/OT



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: ALAN-23NWPP173

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected MCP18x, MCP60x, MCP61x, MCP6Lx, MCP13x, MCP32x, MCP30x, TC74, MCP65x, MCP64x, MCP62x, MCP6Gx, TC118x, TC101x, TC107x, TC105x, TC122x, TC201x, TC218x, and TC205x device families available in 5L SOT-23 package at MTAI assembly site.
CN	E000258686
QUAL ID	R2500130 Rev. A
MP CODE	GBAH1YC8XF33
Part No.	TC1073-3.3VCH713
Bonding No.	BD-002760 Rev. 01
CCB No.	7348.001
<u>Package</u>	
Type	6L SOT-23
<u>Lead Frame</u>	
Paddle size	72 x 41 mils
Material	A194
Surface	Ag single ring Plated
Process	Stamped
Lead Lock	No
Part Number	10100607
Treatment	BOT
<u>Material</u>	
Epoxy	8900NC
Wire	CuPdAu
Mold Compound	G600V
Plating Composition	Matte Sn



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI254201698.000	TMPE225096853.110	2503HW9
MTAI254300989.000	TMPE225096853.110	2504KYH
MTAI254301014.000	TMPE225096853.110	2504M2T

Result

☒ Pass ☐ Fail ☐ _____

6L SOT-23 assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C and 125°C System: TTS	JESD22- A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAIESPEC Model PR-3SPH	J-STD-020E		693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 125°C System: TTS		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAIESPEC TSA-70H Electrical Test: + 125°C System: TTS Bond Strength: Wire Pull (>2.50 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C 77 units / lot
			231(0)	0/231	Pass	
			15(0)	0/15	Pass	
			15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: TTS	JESD22-A118		231		Parts had been pre-conditioned at 260°C 77 units / lot
			231(0)	0/231	Pass	
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: VDD=6.5 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: TTS	JESD22-A110		231		Parts had been pre-conditioned at 260°C 77 units / lot
			231(0)	0/231	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 150°C, 1008 hrs. System: CHINEE	JESD22- A103		135		45 units / lot refer R2500406-1/2/3
	Electrical Test: +25°C and 125°C System: TTS		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC- Q100-001	30(0) Bonds	0/30	Pass	

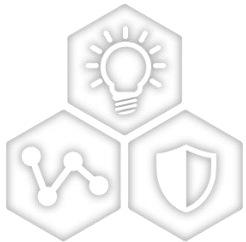
CCB 7348.001

Pre and Post Change Summary

PCN# ALAN-23NWPP173



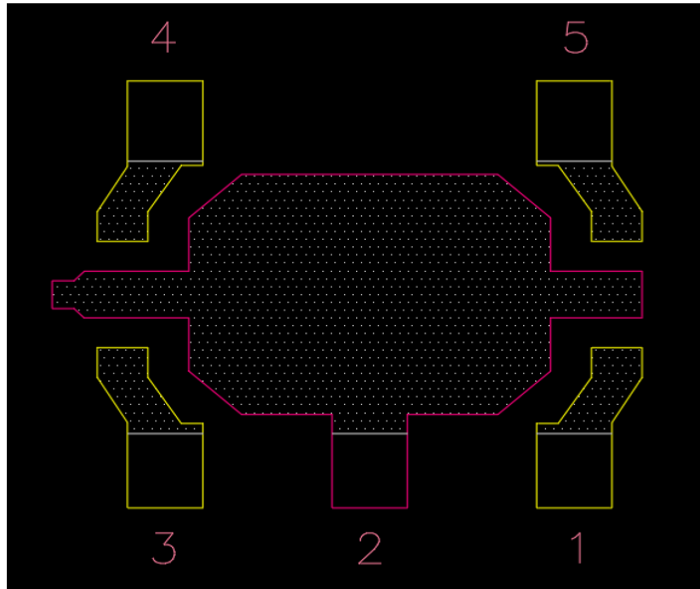
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

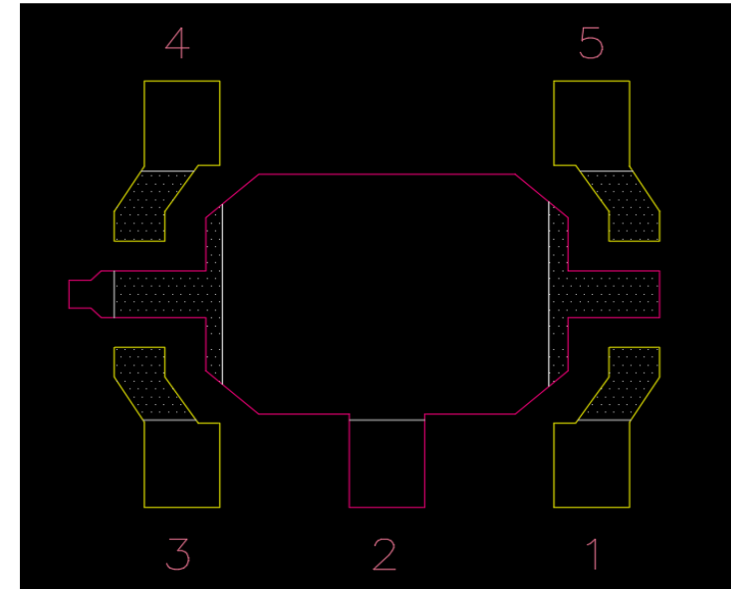
Pre and Post Change Summary

Pre Change



DAP Surface Prep	Ag Spot Plated
Treatment	None

Post Change



DAP Surface Prep	Ag Single Ring Plated
Treatment	BOT

*Not fit to scale